

Electronic Acknowledgement Receipt

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Application Number:	10780932
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Title of Invention:	Interconnect structure for TFT-array substrate and method for fabricating the same
First Named Inventor:	Kun-Hong Chen
Customer Number:	24504
Filer:	Daniel R. McClure
Filer Authorized By:	
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment After Final	00401270.pdf	105018	no	5

Warnings:	
Information:	
Total Files Size (in bytes):	105018
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